TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (U-MOSIV)

# **TPCP8004**

# Notebook PC Applications Portable Equipment Applications

- Small footprint due to a small and thin package
- · High speed switching
- Small gate charge: Qg = 26nC (typ.)
- Low drain-source ON-resistance:  $RDS(ON) = 7m\Omega(typ.)$
- High forward transfer admittance:  $|Y_{fs}| = 21S$  (typ.)
- Low leakage current:  $I_{DSS} = 10\mu A \text{ (max) (V}_{DS} = 30\text{V)}$
- Enhancement mode:  $V_{th} = 1.3 \text{ to } 2.5 \text{V (V}_{DS} = 10 \text{V, I}_{D} = 1 \text{mA})$

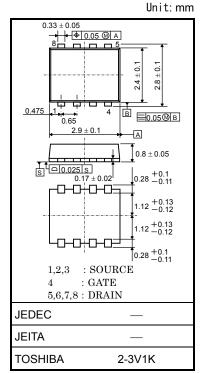
#### Absolute Maximum Ratings (Ta=25°C)

Characte	Symbol	Rating	Unit		
Drain-source voltage	V <sub>DSS</sub>	30	V		
Drain-gate voltage (	R <sub>GS</sub> =20 kΩ)	$V_{DGR}$	30	V	
Gate-source voltage	)	V <sub>GSS</sub>	±20	٧	
Drain current	DC (Note 1)	ID	8.3	Α	
Drain current	Pulse (Note 1)	I <sub>DP</sub>	33.2	A	
Drain power dissipa	PD	1.68	W		
		P <sub>D</sub>	0.84	W	
Single-pulse avalan	E <sub>AS</sub>	17.9	mJ		
Avalanche current	I <sub>AR</sub>	8.3	Α		
Repetitive avalanche energy (Note 4)		E <sub>AR</sub>	0.021	mJ	
Channel temperatur	T <sub>ch</sub>	150	°C		
Storage temperature	T <sub>stg</sub>	-55 to 150	°C		

Note: For Notes 1 to 5, refer to the next page.

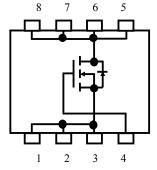
Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

This transistor is an electrostatic-sensitive device. Handle with care.

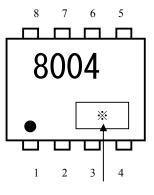


Weight: 0.017g(typ.)

#### **Circuit Configuration**



#### Marking (Note 5)



Lot No.

2008-12-18

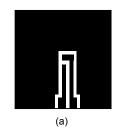
#### **Thermal Characteristics**

Characteristic	Symbol	Max	Unit
Thermal resistance, channel to ambient (t = 5 s) (Note 2a)	R <sub>th (ch-a)</sub>	74.4	°C/W
Thermal resistance, channel to ambient (t = 5 s) (Note 2b)	R <sub>th (ch-a)</sub>	148.8	°C/W

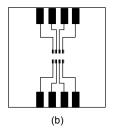
Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: (a) Device mounted on a glass-epoxy board (a)

(b) Device mounted on a glass-epoxy board (b)



FR-4  $25.4 \times 25.4 \times 0.8$  (Unit: mm)



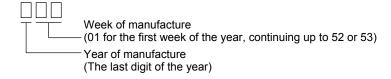
FR-4  $25.4 \times 25.4 \times 0.8$  (Unit: mm)

Note 3:  $V_{DD}$  =24V,  $T_{ch}$  = 25°C (initial), L =0.2mH,  $R_G$  = 1  $\Omega$ ,  $I_{AR}$  =8.3 A

Note 4: Repetitive rating: pulse width limited by max channel temperature

Note 5: • on the lower left of the marking indicates Pin 1.

Weekly code: (Three digits)

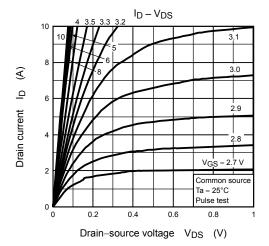


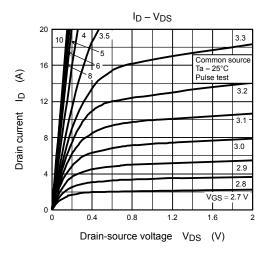
## **Electrical Characteristics (Ta = 25°C)**

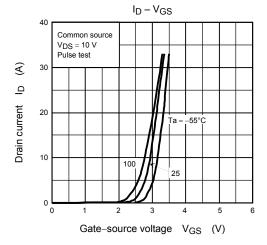
Cha	racteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	Sate leakage current		$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±100	nA
Drain cutoff curr	ent	I <sub>DSS</sub>	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$	10		μΑ	
Drain-source breakdown voltage		V (BR) DSS	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	30	_	_	V
		V (BR) DSX	$I_D = 10 \text{ mA}, V_{GS} = -20 \text{ V}$	10	_	_	v
Gate threshold	voltage	V <sub>th</sub>	$V_{DS} = 10 \text{ V}, I_D = 1\text{mA}$	1.3	_	2.5	V
Drain source Of	N recistance	Ppg (ON)	$V_{GS} = 4.5 \text{ V}, I_D = 4.2 \text{A}$	_	10.5	14	0
Drain-source ON-resistance		R <sub>DS</sub> (ON)	$V_{GS} = 10 \text{ V}, I_D = 4.2 \text{A}$	_	7	8.5	mΩ
Forward transfe	r admittance	Y <sub>fs</sub>	$V_{DS} = 10 \text{ V}, I_D = 4.2 \text{A}$	10	21	_	S
Input capacitand	ce	C <sub>iss</sub>	V= - 40 V V = - 0 V	_	1270	_	
Reverse transfer capacitance		C <sub>rss</sub>	V <sub>DS</sub> =10 V, V <sub>GS</sub> =0 V, f = 1MHz	_	240	_	pF
Output capacitance		Coss	1 - 11VII 12	_	380	_	
Switching time	Rise time	tr	V <sub>GS</sub> 10 V	_	12		· ns
	Turn-on time	t <sub>on</sub>		_	23		
	Fall time	t <sub>f</sub>		_	9	_	
	Turn-off time	t <sub>off</sub>	$V_{DD} \approx 15 \text{ V}$ Duty $\leq$ 1%, $t_W = 10 \mu\text{s}$	_	35	_	
Total gate charge (gate-source plus gate-drain)		Qg	V <sub>DD</sub> ≈ 24 V, V <sub>GS</sub> =10 V,	_	26		nC
Gate-source charge 1		Q <sub>gs1</sub>	I <sub>D</sub> =8.3 A	_	3.8	_	
Gate-drain ("Miller") charge		Q <sub>gd</sub>		_	8	_	

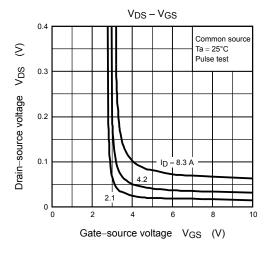
## **Source-Drain Ratings and Characteristics (Ta = 25°C)**

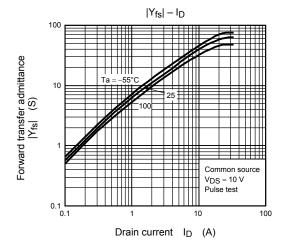
Characteri	stic	Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	I <sub>DRP</sub>	_	_	_	33.2	Α
Forward voltage (diode	e)	$V_{DSF}$	$I_{DR} = 8.3 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	-1.2	V

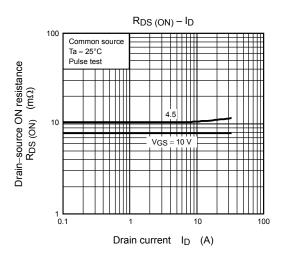


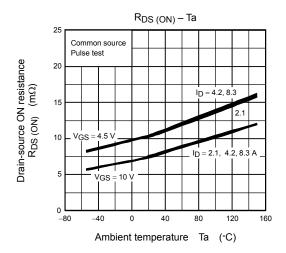


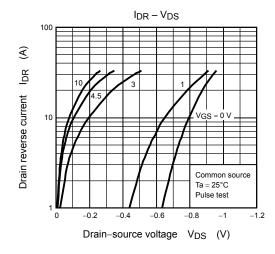


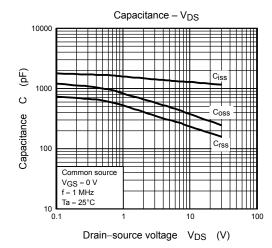


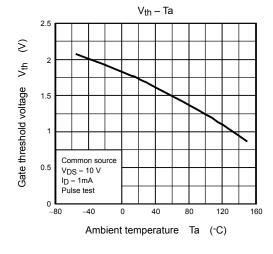


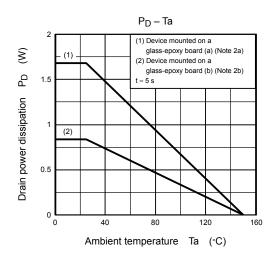


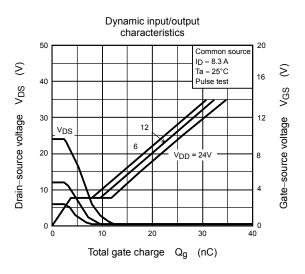


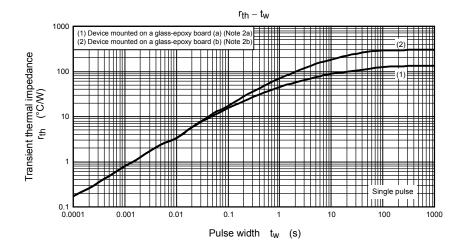


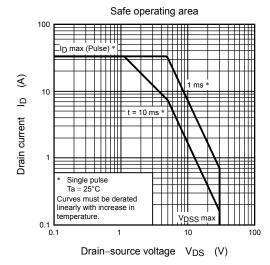












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